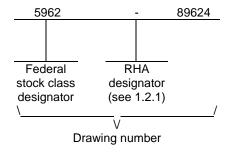
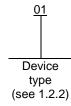
						F	REVISI	ONS										
LTR				DESCR	RIPTIO	٧					DATE (YR-MO-DA)			APPROVED			l	
Α	Add case o					1.2.2, 1	1.3, 6.6	, and fi	gure 1.		91-12-05				M. A. FRYE			
В	Add case o			0 lead fl	lat pack	. Make	e chang	ges to 1	1.2.2, 1.	.3,		97-1	12-09		R. MONNIN			
С	Make chan CMRR test	Make changes to boilerplate to add class level V devices. Make char CMRR test and add a new footnote to Table I. Add Table IIB ro				ange to)		98-0)6-18		R. MONNIN						
D	Deleted fig PRF-38535	Deleted figure 1. Replaced reference to MIL-STD-973 with refe PRF-38535. –rrp				referen	ce to M	IL-	03-05-30			R. MONNIN						
E	Update dra	Update drawing to current requirementsrrp									10-0	08-10			C. SA	AFFLE		
THE ORIGINA REV SHEET REV SHEET	AL FIRST SHEE	ET OF THI	S DRAWI	NG HAS	S BEEN	I REPL	ACED.											
REV SHEET REV			S DRAWI	NG HAS	S BEEN	I REPL	ACED.	E	E	E	E	E	E	E				
REV SHEET REV SHEET	S			NG HAS					E 5	E 6	E 7	E 8	E 9	E 10				
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA	ANDARD		REV SHEET PREPARE RICK C	ED BY	E 1	E 2	E	E		6	7 DLA I	8 LAND	9 ANE, OHIO		218-3	990		
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRO DR THIS DRAW FOR U DEP/ AND AGE	ANDARD	BLE [REV SHEET PREPARE RICK C CHECKEE CHARL	ED BY C. OFFICE D BY LES E. B ED BY EL A. FI	E 1 CER BESORI	E 2	E	E 4	5 CROC	6 CC	7 DLA I DLUM http	BLANDIBUS	9 ANE, OHIO	0 MAR O 432 cc.dla	218-33 a.mil SPE	990		
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A STA MICRI DR THIS DRAW FOR I DEP/ AND AGE DEPARTME	ANDARD OCIRCUIT AWING VING IS AVAILA USE BY ALL ARTMENTS ENCIES OF TH	BLE [REV SHEET PREPARE RICK C CHECKED CHARL MPPROVE MICHA	ED BY C. OFFICE D BY ES E. B ED BY EL A. FI G APPRO 90-0	E 1 CER BESORI	E 2	E	E 4 MIC OP SIL	5 CROC ERA1	6 CCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCC	7 DLA I DLUM http	AND IBUS DE INE	9 ANE, OHIO	MAR O 432 cc.dla	218-3: a.mil SPE NOL	: 990 :ED,		

1. SCOPE

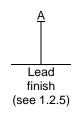
- 1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels is reflected in the PIN.
 - 1.2 PIN. The PIN is as shown in the following examples.

For device classes M and Q:

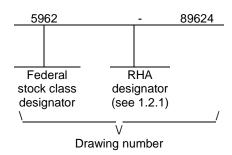


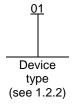


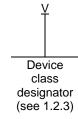


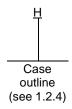


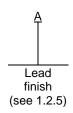
For device class V:











- 1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	LM6164	High speed operational amplifier

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as listed below. Since the device class designator has been added after the original issuance of this drawing, device classes M and Q designators will not be included in the PIN and will not be marked on the device.

Device class

Device requirements documentation

М

Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A

Q or V

Certification and qualification to MIL-PRF-38535

STANDARD
MICROCIRCUIT DRAWING
DLA LAND AND MARITIME
COLUMBUS, OHIO 43218-3990

SIZE A		5962-89624
	REVISION LEVEL E	SHEET 2

1.2.4 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
Н	GDFP1-F10 or CDFP2-F10	10	Flat pack
Р	GDIP1-T8 or CDIP2-T8	8	Dual-in-line
Χ	GDFP1-G10	10	Flat pack with gullwing leads
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 <u>Lead finish</u>. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings. 1/

Supply voltage (V+ to V-)	36 V
Differential input voltage 2/	±8 V
Common-mode voltage	(V+ -0.7 V) to (V7 V)
Output short circuit to GND 3/	Continuous
Operating supply voltage range	4.75 V to 32 V
Power dissipation (P _D) (all cases)	400 mW
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	+260°C
Junction temperature (T _J)	+150°C
Thermal resistance, junction-to-case (θ_{JC}):	
Cases H, P, and X	21°C/W
Case 2	
Thermal resistance, junction-to-ambient (θ_{JA}):	
Cases H and X	228°C/W still air
	140°C/W at 500 linear feet per minute
Case P	113°C/W still air
	51°C/W at 500 linear feet per minute
Case 2	90°C/W still air
	60°C/W at 400 linear feet per minute

1.4 Recommended operating conditions.

Positive supply voltage (V+)	+15 V
Negative supply voltage (V-)	
Ambient operating temperature range (T _A)	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

^{3/} Continuous short-circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of +150°C.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89624
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL E	SHEET 3

^{1/} Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

In order to achieve optimum ac performance, the input stage was designed without protective clamps. Exceeding the maximum differential input voltage results in reverse breakdown of the base-emitter junction of one of the input transistors and probable degradation of the input parameters (especially, V_{IO} and I_{IO}).

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at https://assist.daps.dla.mil/quicksearch/ or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.
 - 3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.4 herein .
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.
- 3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.
- 3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DLA Land and Maritime-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89624
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL E	SHEET 4

TABLE I. <u>Electrical performance characteristics</u>.

Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C unless otherwise specified	Group A subgroups	Device type	Lir	nits	Unit
					Min	Max	1
Input offset voltage	V _{IO}		1	01	-4	4	mV
			2,3	-	-6	6	
Input bias current	I _{IB}		1	01	-3	3	μА
			2,3	-	-6	6	
Input offset current	I _{IO}		1	01	-350	350	nA
			2,3	-	-800	800	
Large signal voltage gain	A _{VS}	V _{OUT} = ±10 V, <u>2</u> /	1	01	1.8		V/mV
		$R_L = 2 \text{ k}\Omega$	2,3	-	0.9		
Positive common-mode voltage range	+V _{CM}	V _S = ±15 V	1	01	13.9		V
voltage range			2,3	1	13.8		
		V _S = ±5 V	1		3.9		V
			2,3	-	3.8		
Negative common-mode voltage range	-V _{CM}	V _S = ±15 V	1	01		-13.3	V
vollage range			2,3	-		-13.1	
		V _S = ±5 V	1	-		-1.7	V
			2,3	-		-1.9	
Common-mode rejection ratio	CMRR	-12.9 V ≤ V _{CM} ≤ +13.9 V	1	01	86		dB
		-12.7 V ≤ V _{CM} ≤ +13.8 V	2,3	•	80		
Power supply rejection ratio	PSRR	±10 V ≤ V _S ≤ ±16 V	1	01	86		dB
			2,3	-	80		1

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89624
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL E	SHEET 5

5

TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test	Symbol		Group A subgroups	Device type	Lir	nits	Unit
			aug.cupc	''	Min	Max	
Positive voltage swing	+V _{OP}	$V_S = \pm 15 \text{ V}, R_L = 2 \text{ k}\Omega$	1	01	13.5		V
			2,3	1	13.3		
		$V_S = \pm 5 \text{ V}, R_L = 2 \text{ k}\Omega$	1	-	3.5		V
			2,3	-	3.3		
Negative voltage swing	-V _{OP}	$V_S = \pm 15 \text{ V}, R_L = 2 \text{ k}\Omega$	1	01		-13.0	V
			2,3	-		-12.7	
		$V_S = \pm 5 \text{ V}, R_L = 2 \text{ k}\Omega$	1	-		-1.7	V
			2,3	-		-2.0	
Output short circuit	I _{OS}	Source	1	01		-30	mA
current			2,3	-		-20	<u> </u>
		Sink	1	<u> </u>	30		mA
			2,3	_	20		<u> </u>
Supply current	Icc		1	01		6.5	mA
			2,3	-		6.8	<u> </u>
Gain bandwidth product	GBW	f = 20 MHz	4	01	140		MHz
			5,6	-	80		<u> </u>
Positive slew rate	+SR	Output step = -10 V to $+10 \text{ V}$, $A_V = +5$,	4	01	200		V/µs
		V _{IN} = 4 V step	5,6	-	180		
Negative slew rate	-SR	Output step = $+10 \text{ V}$ to -10 V , $A_V = +5$,	4	01	200		V/μs
		V _{IN} = 4 V step	5,6	1	180		
Settling time	ts	10 V step to 0.1 %,	9	01		275	ns
		$R_L = 2 k\Omega, A_V = -4$	10,11	1		300	1

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89624
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL E	SHEET 6

Device type	01		
Case outlines	H and X	Р	2
Terminal number	Terminal symbol		
1	NC	V _{IO} ADJ	NC
2	V _{IO} ADJ	INV INPUT	V _{IO} ADJ
3	INV INPUT	NONINV INPUT	NC
4	NONINV INPUT	V-	NC
5	V-	NC	INV INPUT
6	NC	V_{OUT}	NC
7	V _{OUT}	V+	NONINV INPUT
8	V+	V _{IO} ADJ	NC
9	V _{IO} ADJ		NC
10	NC		V-
11			NC
12			NC
13			NC
14			NC
15			V _{OUT}
16			NC
17			V+
18			NC
19			NC
20			V _{IO} ADJ

FIGURE 1. <u>Terminal connections</u>.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89624
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL E	SHEET 7

- 3.8 <u>Notification of change for device class M.</u> For device class M, notification to DLA Land and Maritime-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.
- 3.9 <u>Verification and review for device class M.</u> For device class M, DLA Land and Maritime, DLA Land and Maritime 's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device class M.</u> Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

4. VERIFICATION

- 4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.
 - 4.2.1 Additional criteria for device class M.
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.
- 4.3 <u>Qualification inspection for device classes Q and V.</u> Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
- 4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89624
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL E	SHEET 8

TABLE IIA. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgr (in accord MIL-PRF-385	ance with
	Device	Device	Device
	class M	class Q	class V
Interim electrical	1	1	1
parameters (see 4.2)			
Final electrical	1,2,3,4,5,6 <u>1</u> /	1,2,3,4,5,6 <u>1</u> /	1,2,3, <u>1</u> /
parameters (see 4.2)			4,5,6
Group A test	1,2,3,4,5,6,	1,2,3,4,5,6	1,2,3,4,5,6,
requirements (see 4.4)	9,10,11	9,10,11	9,10,11
Group C end-point electrical parameters (see 4.4)	1,2,3	1,2,3	1,2,3 <u>2</u> /
Group D end-point electrical	1,2,3	1,2,3	1,2,3
parameters (see 4.4)			
Group E end-point electrical			
parameters (see 4.4)			

^{1/} PDA applies to subgroup 1.

TABLE IIB. Operating life test delta parameters. T_A = +25°C

Parameter	Symbol	Limit	Unit
Input offset voltage	V _{IO}	±0.6	mV
Input bias current	I _{IB}	±0.5	μΑ
Input offset current	I _{IO}	±35	nA
Common mode rejection ratio	CMRR	±5	dB

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 7 and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
- 4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:
 - a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - b. $T_A = +125$ °C, minimum.
 - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89624
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL E	SHEET 9

Delta limits (see table IIB) shall be required and the delta values shall be computed with reference to the previous endpoint electrical parameters.

- 4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - 4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.
- 4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).
 - a. End-point electrical parameters shall be as specified in table IIA herein.
 - b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25°C ±5°C, after exposure, to the subgroups specified in table IIA herein.

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.3 <u>Record of users</u>. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and which SMD's are applicable to that system. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime-VA, telephone (614) 692-0547.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DLA Land and Maritime-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0540.
- 6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.
 - 6.6 Sources of supply.
- 6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DLA Land and Maritime-VA and have agreed to this drawing.
- 6.6.2 <u>Approved sources of supply for device class M.</u> Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime-VA.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-89624
DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990		REVISION LEVEL E	SHEET 10

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 10-08-10

Approved sources of supply for SMD 5962-89624 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime -VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at http://www.dscc.dla.mil/Programs/Smcr/.

Standard microcircuit drawing PIN 1/	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8962401HA	<u>3</u> /	LM6164W/883
5962-8962401PA	<u>3</u> /	LM6164J/883
5962-8962401XA	<u>3</u> /	LM6164WG/883
5962-89624012A	<u>3</u> /	LM6164E/883
5962-8962401VPA	<u>3</u> /	LM6164J-QMLV
5962-8962401VXA	<u>3</u> /	LM6164WG-QMLV

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply. The last known supplier is listed below.

Vendor CAGE <u>number</u>

Vendor name and address

27014

National Semiconductor Corporation 2900 Semiconductor Drive P.O. Box 58090 Santa Clara, CA 95052-8090

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.